| | | |
|---|---|---|
| IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® | **Material Composition Declaration**<br>© Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions. | This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility. |

| | | | |
|---|---|---|---|
| 1752-21.1 | IPC Web Site for Information on IPC-1752 Standard<br>**http://www.ipc.org/IPC-175x** | Form Type *<br>Distribute | Declaration Class *<br>Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information |

## Supplier Information

| | | | |
|---|---|---|---|
| **Company name***<br>**onsemi** | Company unique ID | Unique ID Authority | **Response Date***<br>**2026-07-04** |
| **Contact Name**<br>**Product-Env-Stewards** | Title - Contact<br>Product Enviro Compliance | **Phone - Contact***<br>**NA** | **Email - Contact***<br>**Product-Env-Stewards@onsemi.com** |
| **Authorized Representative***<br>**Product-Env-Stewards** | Title - Representative<br>Product Enviro Compliance | **Phone - Representative***<br>**NA** | **Email - Representative***<br>**Product-Env-Stewards@onsemi.com** |

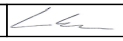
| | Requester Item Number | Mfr Item Number | Mfr Item Name | Effective Date | Version | Manufacturing Site | Weight* | UOM | Unit Type |
|---|---|---|---|---|---|---|---|---|---|
| | | NFAM5312SCBUT | SiC M3 1200V 53mohm SPM31 | 2026-07-04 | | VN5 | 8935.35 | mg | Each |

## Manufacturing Proccess Information

| | Terminal Plating / Grid Array Material | Terminal Base Alloy | J-STD-020 MSL Rating | Peak Process Body Temperature | | Max Time at Peak Temperature | | Number of Reflow Cycles |
|---|---|---|---|---|---|---|---|---|
| | **Matte Tin (Sn) - annealed** | **CU Alloy** | **NA** | **0** | C | **30** | seconds | **3** |

Comments

**For more information regarding material composition please refer to page 3**

| **RoHS Material Composition Declaration** | | **Declaration Type *** | **Detailed** |
|---|---|---|---|
| Directive 2015/863/EU amending RoHS Directive 2011/65/EU | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP). | | |
| Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a “RoHS restricted substance”) in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components.Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form.Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, itssuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph.If the Company and the Supplier enter into a written agreement with respect to the identified part,the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply. | | | |
| **RoHS Declaration *** | 4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions | **Supplier Acceptance *** | **Accepted** |
| **Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).** | | | |
| Exemption List Version | EL-2011/534/EU | | |
| **Declaration Signature** | | | |
| **Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.** | | | |
| Supplier Digital Signature | **Rastislav Drska** |  | |

**Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

| Homogeneous Material | Weight | Unit of Measure | Level | Substance | CAS | Exempt | Weight | Unit of Measure |
|---|---|---|---|---|---|---|---|---|
| DBC | 461.07 | mg | Supplier | Aluminum Trioxide (Al2O3) | 1344-28-1 | | 184.428 | mg |
| | | | Supplier | Copper (Cu) | 7440-50-8 | | 276.642 | mg |
| Die | 25.49 | mg | Supplier | Silicon (Si) | 7440-21-3 | | 25.49 | mg |
| Die Attach | 1.41 | mg | | Epoxy resin | proprietary data | | 0.2171 | mg |
| | | | Supplier | Imidazole Addition | 68490-66-4 | | 0.0226 | mg |
| | | | Supplier | Silver (Ag) | 7440-22-4 | | 1.0857 | mg |
| | | | B | Bismuth Trioxide (Bi2O3) | 1304-76-3 | | 0.0606 | mg |
| | | | B | Antimony Pentoxide (Sb2O5) | 1314-60-9 | | 0.024 | mg |
| Die Attach Solder | 4.2 | mg | Supplier | Silver (Ag) | 7440-22-4 | | 0.105 | mg |
| | | | Supplier | Tin (Sn) | 7440-31-5 | | 4.074 | mg |
| | | | Supplier | Copper (Cu) | 7440-50-8 | | 0.021 | mg |
| Die SiC | 17.1 | mg | Supplier | Silicon Carbide | 409-21-2 | | 17.1 | mg |
| Lead Frame | 462.34 | mg | Supplier | Silver (Ag) | 7440-22-4 | | 23.117 | mg |
| | | | Supplier | Zinc (Zn) | 7440-66-6 | | 0.5548 | mg |
| | | | Supplier | Iron (Fe) | 7439-89-6 | | 11.0962 | mg |
| | | | Supplier | Copper (Cu) | 7440-50-8 | | 427.2022 | mg |
| | | | Supplier | Phosphorus (P) | 7723-14-0 | | 0.3698 | mg |
| Mold Compound | 7922.92 | mg | | Organic Compound | proprietary data | | 237.6876 | mg |
| | | | Supplier | Metal Hydroxide | Proprietary Data | | 475.3752 | mg |
| | | | Supplier | Ortho Cresol Novolac Resin | 29690-82-2 | | 1109.2087 | mg |
| | | | Supplier | Carbon Black (C) | 1333-86-4 | | 39.6146 | mg |
| | | | Supplier | Fused Silica (SiO2) | 60676-86-0 | | 5546.0439 | mg |
| | | | Supplier | Phenolic Resin (Novolac) | 9003-35-4 | | 514.9897 | mg |
| NTC | 4.7 | mg | Supplier | Titanium Dioxide (TiO2) | 13463-67-7 | | 0.2002 | mg |
| | | | Supplier | Silver (Ag) | 7440-22-4 | | 0.047 | mg |
| | | | Supplier | Boron Trioxide (B2O3) | 1303-86-2 | | 0.0122 | mg |
| | | | Supplier | Tin (Sn) | 7440-31-5 | | 0.078 | mg |
| | | | Supplier | Nickel Oxide (NiO) | 1313-99-1 | | 1.0006 | mg |
| | | | Supplier | Silica Amorphous (SiO2) | 7631-86-9 | | 0.0348 | mg |
| | | | Supplier | Palladium (Pd) | 7440-05-3 | | 0.11 | mg |
| | | | Supplier | Iron Trioxide (Fe2O3) | 1309-37-1 | | 0.2002 | mg |
| | | | B | Nickel (Ni) | 7440-02-0 | | 0.0334 | mg |

| | | | | | | | | |
|---|---|---|---|---|---|---|---|---|
| | | | Supplier | Manganese Tetraoxide (Mn3O4) | 1317-35-7 | | 2.6019 | mg |
| | | | Supplier | Copper (Cu) | 7440-50-8 | | 0.3816 | mg |
| Plating | 0.17 | mg | Supplier | Tin (Sn) | 7440-31-5 | | 0.17 | mg |
| Solder Wire | 7.24 | mg | A | Lead (Pb) | 7439-92-1 | 7a | 6.878 | mg |
| | | | Supplier | Tin (Sn) | 7440-31-5 | | 0.362 | mg |
| Wire Bond - Al | 28.58 | mg | Supplier | Aluminum (Al) | 7429-90-5 | | 28.58 | mg |
| Wire Bond - Cu | 0.13 | mg | Supplier | Copper (Cu) | 7440-50-8 | | 0.13 | mg |